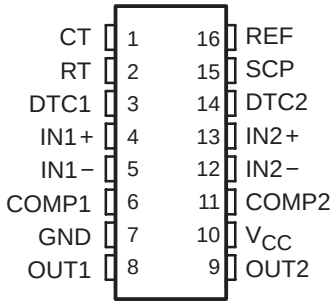
- **Two Complete PWM Control Circuits**
- **Outputs Drive MOSFETs Directly**
- **Oscillator Frequency . . . 50 kHz to 2 MHz**
- **3.6-V to 20-V Supply-Voltage Range**
- **Low Supply Current . . . 3.5 mA Typ**
- **Adjustable Dead-Time Control, 0% to 100%**
- **1.26-V Reference**

D, N OR PW PACKAGE
(TOP VIEW)



description

The TL1454A is a dual-channel pulse-width-modulation (PWM) control circuit, primarily intended for low-power, dc/dc converters. Applications include LCD displays, backlight inverters, notebook computers, and other products requiring small, high-frequency, dc/dc converters.

Each PWM channel has its own error amplifier, PWM comparator, dead-time control comparator, and MOSFET driver. The voltage reference, oscillator, undervoltage lockout, and short-circuit protection are common to both channels.

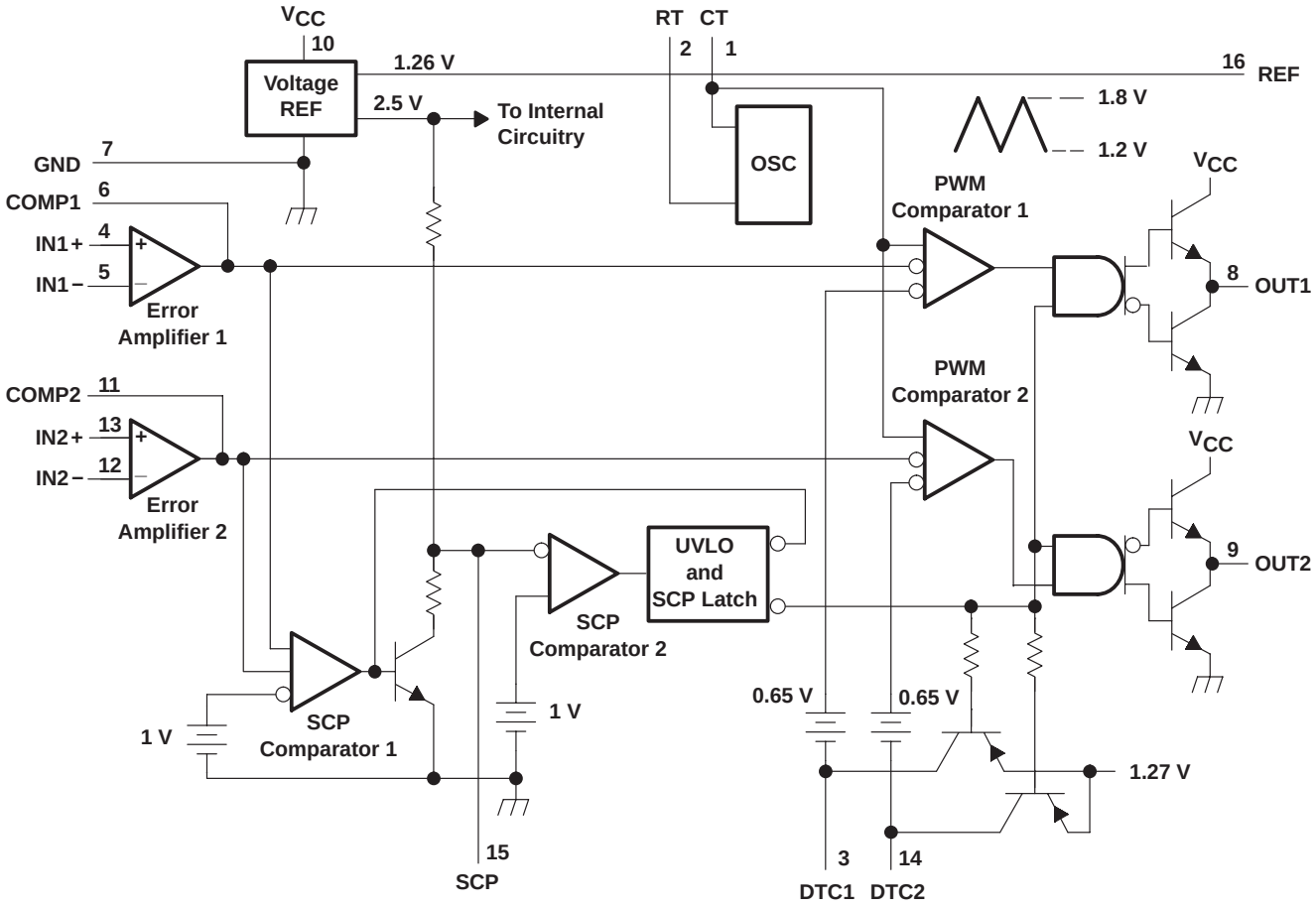
Channel 1 is configured to drive n-channel MOSFETs in step-up or flyback converters, and channel 2 is configured to drive p-channel MOSFETs in step-down or inverting converters. The operating frequency is set with an external resistor and an external capacitor, and dead time is continuously adjustable from 0 to 100% duty cycle with a resistive divider network. Soft start can be implemented by adding a capacitor to the dead-time control (DTC) network. The error-amplifier common-mode input range includes ground, which allows the TL1454A to be used in ground-sensing battery chargers as well as voltage converters.

AVAILABLE OPTIONS

T_A	PACKAGED DEVICES†					CHIP FORM (Y)
	SMALL OUTLINE (D)	PLASTIC DIP (N)	TSSOP (PW)	SSOP (DB)	SOP-EIAJ (NS)	
–20°C to 85°C	TL1454ACD	TL1454ACN	TL1454ACPWR	TL1454ACDB	TL1454ACNS	TL1454AY

† The D, DB and NS packages are available taped and reeled. Add the suffix R to the device name (e.g., TL1454ACDR). The PW package is available only left-end taped and reeled (indicated by the R suffix on the device type; e.g., TL1454ACPWR).

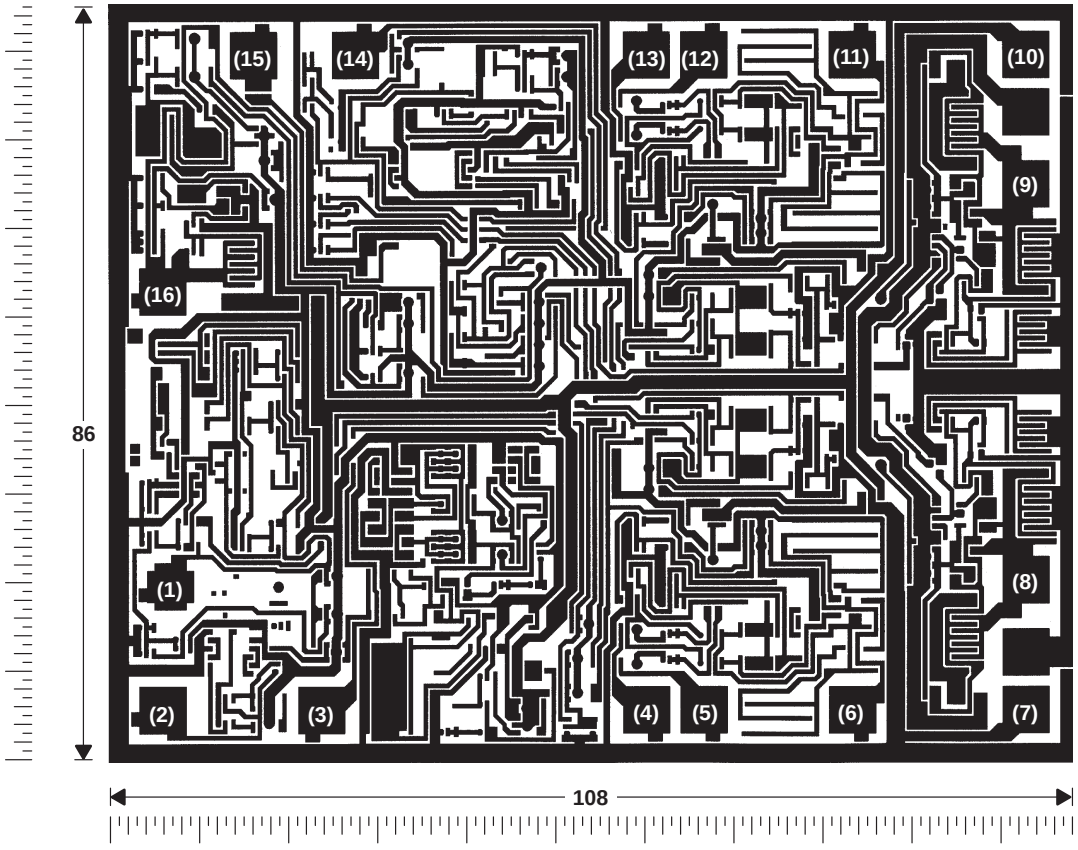
functional block diagram

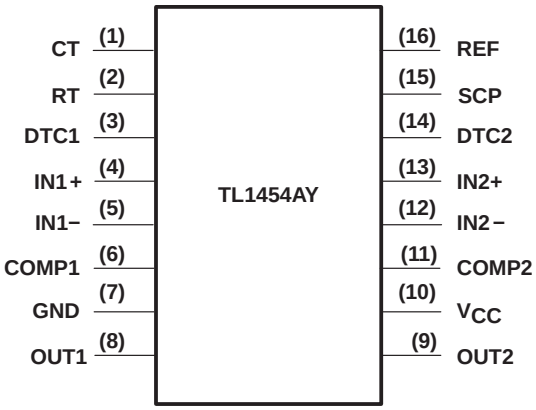


TL1454AY chip information

This device, when properly assembled, displays characteristics similar to the TL1454AC. Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.

BONDING PAD ASSIGNMENTS





CHIP THICKNESS: 15 TYPICAL

BONDING PADS: 4 × 4 MINIMUM

$T_J$max = 150°C

TOLERANCES ARE ±10%.

ALL DIMENSIONS ARE IN MILS.

theory of operation

reference voltage

A linear regulator operating from V_{CC} generates a 2.5-V supply for the internal circuits and the 1.26-V reference, which can source a maximum of 1 mA for external loads. A small ceramic capacitor (0.047 μF to 0.1 μF) between REF and ground is recommended to minimize noise pickup.

error amplifier

The error amplifier generates the error signal used by the PWM to adjust the power-switch duty cycle for the desired converter output voltage. The signal is generated by comparing a sample of the output voltage to the voltage reference and amplifying the difference. An external resistive divider connected between the converter output and ground, as shown in Figure 1, is generally required to obtain the output voltage sample.

The amplifier output is brought out on COMP to allow the frequency response of the amplifier to be shaped with an external RC network to stabilize the feedback loop of the converter. DC loading on the COMP output is limited to 45 μA (the maximum amplifier source current capability).

Figure 1 illustrates the sense-divider network and error-amplifier connections for converters with positive output voltages. The divider network is connected to the noninverting amplifier input because the PWM has a phase inversion; the duty cycle decreases as the error-amplifier output increases.

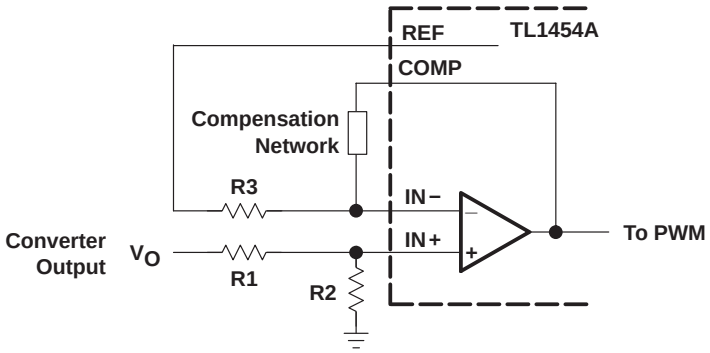


Figure 1. Sense Divider/Error Amplifier Configuration for Converters with Positive Outputs

The output voltage is given by:

$$V_O = V_{ref}\left(1 + \frac{R1}{R2}\right)$$

where V_{ref} = 1.26 V.

The dc source resistance of the error-amplifier inputs should be 10 kΩ or less and approximately matched to minimize output voltage errors caused by the input-bias current. A simple procedure for determining appropriate values for the resistors is to choose a convenient value for R3 (10 kΩ or less) and calculate R1 and R2 using:

$$R_1 = \frac{R_3 V_O}{V_O - V_{ref}}$$

$$R_2 = \frac{R_3 V_O}{V_{ref}}$$

error amplifier

R1 and R2 should be tight-tolerance (±1% or better) devices with low and/or matched temperature coefficients to minimize output voltage errors. A device with a ±5% tolerance is suitable for R3.

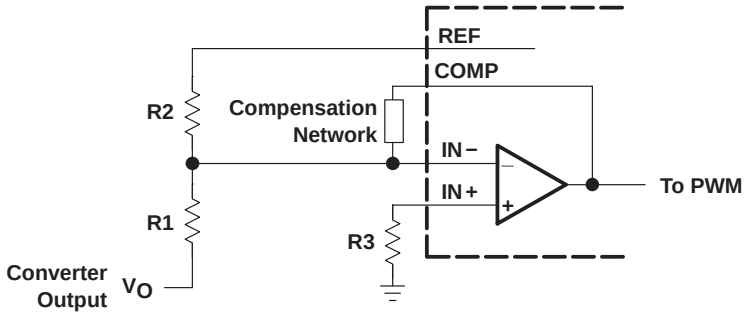


Figure 2. Sense Divider/Error Amplifier Configuration for Converters with Negative Outputs

Figure 2 shows the divider network and error-amplifier configuration for negative output voltages. In general, the comments for positive output voltages also apply for negative outputs. The output voltage is given by:

$$V_O = -\frac{R_1 V_{ref}}{R_2}$$

The design procedure for choosing the resistor value is to select a convenient value for R2 (instead of R3 in the procedure for positive outputs) and calculate R1 and R3 using:

$$R_1 = -\frac{R_2 V_O}{V_{ref}}$$

$$R_3 = \frac{R_1 R_2}{R_1 + R_2}$$

Values in the 10-kΩ to 20-kΩ range work well for R2. R3 can be omitted and the noninverting amplifier connected to ground in applications where the output voltage tolerance is not critical.

oscillator

The oscillator frequency can be set between 50 kHz and 2 MHz with a resistor connected between RT and GND and a capacitor between CT and GND (see Figure 3). Figure 6 is used to determine R_T and C_T for the desired operating frequency. Both components should be tight-tolerance, temperature-stable devices to minimize frequency deviation. A 1% metal-film resistor is recommended for R_T, and a 10%, or better, NPO ceramic capacitor is recommended for C_T.

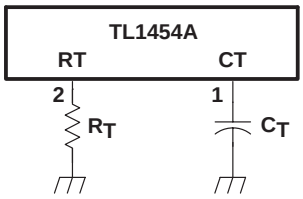


Figure 3. Oscillator Timing

dead-time control (DTC) and soft start

The two PWM channels have independent dead-time control inputs so that the maximum power-switch duty cycles can be limited to less then 100%. The dead-time is set with a voltage applied to DTC; the voltage is typically obtained from a resistive divider connected between the reference and ground as shown in Figure 4. Soft start is implemented by adding a capacitor between REF and DTC.

The voltage, V_{DT}, required to limit the duty cycle to a maximum value is given by:

$$V_{DT} = V_{O(max)} - D\left(V_{O(max)} - V_{O(min)}\right) - 0.65$$

where $V_{O(max)}$ and $V_{O(min)}$ are obtained from Figure 9, and D is the maximum duty cycle.

Predicting the regulator startup or rise time is complicated because it depends on many variables, including: input voltage, output voltage, filter values, converter topology, and operating frequency. In general, the output will be in regulation within two time constants of the soft-start circuit. A five-to-ten millisecond time constant usually works well for low-power converters.

The DTC input can be grounded in applications where achieving a 100% duty cycle is desirable, such as a buck converter with a very low input-to-output differential voltage. However, grounding DTC prevents the implementation of soft start, and the output voltage overshoot at power-on is likely to be very large. A better arrangement is to omit R_{DT1} (see Figure 4) and choose R_{DT2} = 47 kΩ. This configuration ensures that the duty cycle can reach 100% and still allows the designer to implement soft start using C_{SS}.

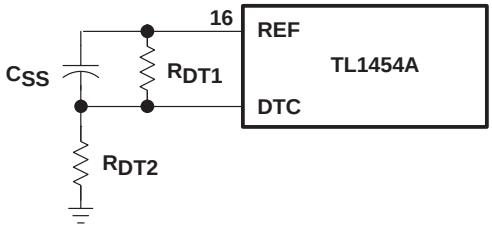


Figure 4. Dead-Time Control and Soft Start

PWM comparator

Each of the PWM comparators has dual inverting inputs. One inverting input is connected to the output of the error amplifier; the other inverting input is connected to the DTC terminal. Under normal operating conditions, when either the error-amplifier output or the dead-time control voltage is higher than that for the PWM triangle wave, the output stage is set inactive (OUT1 low and OUT2 high), turning the external power stage off.

undervoltage-lockout (UVLO) protection

The undervoltage-lockout circuit turns the output circuit off and resets the SCP latch whenever the supply voltage drops too low (to approximately 2.9 V) for proper operation. A hysteresis voltage of 200 mV eliminates false triggering on noise and chattering.

short-circuit protection (SCP)

The TL1454A SCP function prevents damage to the power switches when the converter output is shorted to ground. In normal operation, SCP comparator 1 clamps SCP to approximately 185 mV. When one of the converter outputs is shorted, the error amplifier output (COMP) will be driven below 1 V to maximize duty cycle and force the converter output back up. When the error amplifier output drops below 1 V, SCP comparator 1 releases SCP, and capacitor, C_{SCP}, which is connected between SCP and GND, begins charging. If the error-amplifier output rises above 1 V before C_{SCP} is charged to 1 V, SCP comparator 1 discharges C_{SCP} and normal operation resumes. If C_{SCP} reaches 1 V, SCP comparator 2 turns on and sets the SCP latch, which turns off the output drives and resets the soft-start circuit. The latch remains set until the supply voltage is lowered to 2 V or less, or C_{SCP} is discharged externally.

short-circuit protection (SCP) (continued)

The SCP time-out period must be greater than the converter start-up time or the converter will not start. Because high-value capacitor tolerances tend to be ±20% or more and IC resistor tolerances are loose as well, it is best to choose an SCP time-out period 10-to-15 times greater than the converter startup time. The value of C_{SCP} may be determined using Figure 6, or it can be calculated using:

$$C_{SCP} = \frac{T_{SCP}}{80.3}$$

where C_{SCP} is in µF and T_{SCP} is the time-out period in ms.

output stage

The output stage of the TL1454A is a totem-pole output with a maximum source/sink current rating of 40 mA and a voltage rating of 20 V. The output is controlled by a complementary output AND gate and is turned on (sourcing current for OUT1, sinking current for OUT2) when all the following conditions are met: 1) the oscillator triangle wave voltage is higher than both the DTC voltage and the error-amplifier output voltage, 2) the undervoltage-lockout circuit is inactive, and 3) the short-circuit protection circuit is inactive.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 23 V
Error amplifier input voltage: IN1+, IN1−, IN2+, IN2− . . . . . 23 V
Output voltage: OUT1, OUT2 . . . . . 20 V
Continuous output current: OUT1, OUT2 . . . . . ±200 mA
Peak output current: OUT1, OUT2 . . . . . 1 A
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: C suffix . . . . . −20°C to 85°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network GND.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW
DB	1000 mW	8.0 mW/°C	640 mW	520 mW
N	1250 mW	10.0 mW/°C	800 mW	650 mW
NS	1953 mW	15.6 mW/°C	1250 mW	1015 mW
PW	500 mW	4.0 mW/°C	320 mW	260 mW

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V_{CC}		3.6	20	V
Error amplifier common-mode input voltage		−0.2	1.45	V
Output voltage, V_O			20	V
Output current, I_O			±40	mA
COMP source current			−45	μA
COMP sink current			100	μA
Reference output current			1	mA
COMP dc load resistance		100		kΩ
Timing capacitor, C_T		10	4000	pF
Timing resistor, R_T		5.1	100	kΩ
Oscillator frequency		50	2000	kHz
Operating free-air temperature, T_A	TL1454AC	−20	85	°C

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 6 V, f_{osc} = 500 kHz (unless otherwise noted)

reference

PARAMETER		TEST CONDITIONS		TL1454A MIN	TL1454A TYP	TL1454A MAX	UNIT
V_{ref}	Output voltage, REF	I_O = 1 mA,	T_A = 25°C	1.22	1.26	1.32	V
		I_O = 1 mA		1.20		1.34	
	Input regulation	V_{OC} = 3.6 V to 20 V,	I_O = 1 mA		2	6	mV
	Output regulation	I_O = 0.1 mA to 1 mA			1	7.5	mV
	Output voltage change with temperature	T_A = $T_{A(min)}$ to 25°C,	I_O = 1 mA	−12.5	−1.25	12.5	mV
		T_A = 25°C to 85°C,	I_O = 1 mA	−12.5	−2.5	12.5	
I_{OS}	Short-circuit output current	V_{ref} = 0 V			30		mA

undervoltage lockout (UVLO)

PARAMETER		TEST CONDITIONS	TL1454A MIN	TL1454A TYP	TL1454A MAX	UNIT
V_{IT+}	Positive-going threshold voltage	T_A = 25°C		2.9		V
V_{IT-}	Negative-going threshold voltage			2.7		V
V_{hys}	Hysteresis, $V_{IT+} - V_{IT-}$		100	200		mV

short-circuit protection (SCP)

PARAMETER		TEST CONDITIONS		TL1454A MIN	TL1454A TYP	TL1454A MAX	UNIT
V_{IT}	Input threshold voltage	T_A = 25°C		0.93	1	1.07	V
V_{stby}†	Standby voltage	No pullup		140	185	230	mV
$V_{I(latched)}$	Latched-mode input voltage				60	120	mV
$V_{IT(COMP)}$	Comparator threshold voltage	COMP1, COMP2			1		V
	Input source current	T_A = 25°C,	$V_{O(SCP)}$ = 0	−5	−15	−20	μA

† This symbol is not presently listed within EIA / JEDEC standards for semiconductor symbology.

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 6 V, f_{osc} = 500 kHz (unless otherwise noted) (continued)

oscillator

PARAMETER		TEST CONDITIONS	TL1454A			UNIT
			MIN	TYP	MAX	
f_{osc}	Frequency	C_T = 120 pF, R_T = 10 kΩ		500		kHz
	Standard deviation of frequency			50		kHz
	Frequency change with voltage	V_{CC} = 3.6 V to 20 V, T_A = 25°C		10		kHz
	Frequency change with temperature	$T_A = T_{A(min)}$ to 25°C		−2	±30	kHz
		T_A = 25°C to 85°C		−10	±30	
	Maximum ramp voltage			1.8		V
	Minimum ramp voltage			1.1		V

dead-time control (DTC)

PARAMETER		TEST CONDITIONS	TL1454A			UNIT
			MIN	TYP	MAX	
V_{IT}	Input threshold voltage	Duty cycle = 0%	0.98	1.1	1.22	V
		Duty cycle = 100%	0.38	0.5	0.62	
$V_{I(latched)}$	Latched-mode input voltage			1.2		V
I_{IB}	Common-mode input bias current	DTC1, IN1+ ≈ 1.2 V			4	µA
	Latched-mode (source) current	T_A = 25°C		−100		µA

error-amplifier

PARAMETER		TEST CONDITIONS	TL1454A			UNIT
			MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 1.25 V, V_{IC} = 1.25 V			6	mV
I_{IO}	Input offset current				100	nA
I_{IB}	Input bias current			−160	−500	nA
V_{ICR}	Input voltage range	V_{CC} = 3.6 V to 20 V	−0.2 to 1.40			V
A_V	Open-loop voltage gain	R_{FB} = 200 kΩ	70	80		dB
	Unity-gain bandwidth			3		MHz
CMRR	Common-mode rejection ratio		60	80		dB
$V_{OM(max)}$	Positive output voltage swing		2.3	2.43		V
$V_{OM(min)}$	Negative output voltage swing			0.63	0.8	
I_{O+}	Output sink current	V_{ID} = −0.1 V, V_O = 1.20 V	0.1	0.5		mA
I_{O-}	Output source current	V_{ID} = 0.1 V, V_O = 1.80 V	−45	−70		µA

output

PARAMETER		TEST CONDITIONS	TL1454A			UNIT
			MIN	TYP	MAX	
V_{OH}	High-level output voltage	I_O = −8 mA	V_{CC}−2	4.5		V
		I_O = −8 mA @ V_{CC} = >10 V	V_{CC}−2.3 V			
		I_O = −40 mA	V_{CC}−2	4.4		
		I_O = 40 mA @ V_{CC} = >10 V	V_{CC}−2.3 V			
V_{OL}	Low-level output voltage	I_O = 8 mA		0.1	0.4	V
		I_O = 40 mA		1.8	2.5	
t_{rv}	Output voltage rise time	C_L = 2000 pF, T_A = 25°C		220		ns
t_{fv}	Output voltage fall time			220		

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 6 V, f_{osc} = 500 kHz (unless otherwise noted) (continued)

supply current

PARAMETER		TEST CONDITIONS	TL1454A			UNIT
			MIN	TYP	MAX	
$I_{CC(stby)}$	Standby supply current	RT open, CT = 1.5 V, No load, V_O (COMP1, COMP2) = 1.25 V,		3.1	6	mA
$I_{CC(average)}$	Average supply current	R_T = 10 kΩ, C_T = 120 pF, 50% duty cycle, Outputs open		3.5	7	mA

electrical characteristics, V_{CC} = 6 V, f_{osc} = 500 kHz, T_A = 25°C (unless otherwise noted)

reference

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
V_{ref}	Output voltage, REF	I_O = 1 mA		1.26		V
	Input regulation	V_{OC} = 3.6 V to 20 V, I_O = 1 mA		2		mV
	Output regulation	I_O = 0.1 mA to 1 mA		1		mV
	Output voltage change with temperature	I_O = 1 mA		−1.25		mV
		I_O = 1 mA		−2.5		
I_{OS}	Short-circuit output current	V_{ref} = 0 V		30		mA

undervoltage lockout (UVLO)

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
V_{IT+}	Positive-going threshold voltage			2.9		V
V_{IT-}	Negative-going threshold voltage			2.7		V
V_{hys}	Hysteresis, $V_{IT+} - V_{IT-}$			200		mV

short-circuit protection (SCP)

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
V_{IT}	Input threshold voltage			1		V
V_{stby}†	Standby voltage	No pullup		185		mV
$V_{I(latched)}$	Latched-mode input voltage			60		mV
$V_{IT(COMP)}$	Comparator threshold voltage	COMP1, COMP2		1		V
	Input source current	$V_{O(SCP)}$ = 0		−15		μA

† This symbol is not presently listed within EIA / JEDEC standards for semiconductor symbology.

oscillator

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
f_{osc}	Frequency	C_T = 120 pF, R_T = 10 kΩ		500		kHz
	Standard deviation of frequency			50		kHz
	Frequency change with voltage	V_{CC} = 3.6 V to 20 V		10		kHz
	Frequency change with temperature	$T_A = T_{A(min)}$ to 25°C		−2		kHz
		T_A = 25°C to 85°C		−10		
	Maximum ramp voltage			1.8		V
	Minimum ramp voltage			1.1		V

electrical characteristics, V_{CC} = 6 V, f_{osc} = 500 kHz, T_A = 25°C (unless otherwise noted) (continued)

dead-time control (DTC)

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
V_{IT}	Input threshold voltage	Duty cycle = 0%		1.1		V
		Duty cycle = 100%		0.5		
$V_{I(latched)}$	Latched-mode input voltage			1.2		V
	Latched-mode (source) current			–100		µA

error-amplifier

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
I_{IB}	Input bias current	V_O = 1.25 V, V_{IC} = 1.25 V		–160		nA
A_V	Open-loop voltage gain	R_{FB} = 200 kΩ		80		dB
	Unity-gain bandwidth			3		MHz
CMRR	Common-mode rejection ratio			80		dB
$V_{OM(max)}$	Positive output voltage swing			2.43		V
$V_{OM(min)}$	Negative output voltage swing			0.63		
I_{O+}	Output sink current	V_{ID} = –0.1 V, V_O = 1.20 V		0.5		mA
I_{O-}	Output source current	V_{ID} = 0.1 V, V_O = 1.80 V		–70		µA

output

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
V_{OH}	High-level output voltage	I_O = –8 mA		4.5		V
		I_O = –40 mA		4.4		
V_{OL}	Low-level output voltage	I_O = 8 mA		0.1		V
		I_O = 40 mA		1.8		
t_{rv}	Output voltage rise time	C_L = 2000 pF		220		ns
t_{fv}	Output voltage fall time			220		

supply current

PARAMETER		TEST CONDITIONS	TL1454AY			UNIT
			MIN	TYP	MAX	
$I_{CC(stby)}$	Standby supply current	RT open, CT = 1.5 V, No load, V_O (COMP1, COMP2) = 1.25 V,		3.1		mA
$I_{CC(average)}$	Average supply current	R_T = 10 kΩ, C_T = 120 pF, 50% duty cycle, Outputs open		3.5		mA

PARAMETER MEASUREMENT INFORMATION

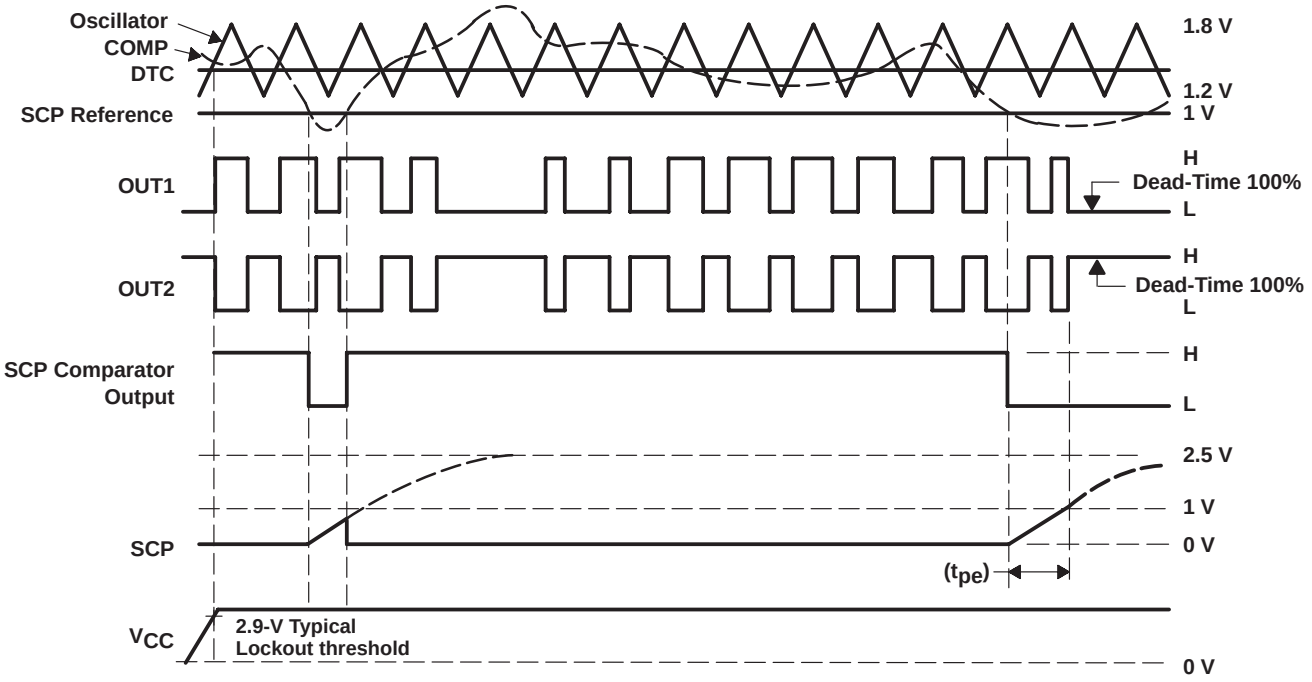


Figure 5. Timing Diagram

TYPICAL CHARACTERISTICS

OSCILLATOR FREQUENCY vs TIMING RESISTANCE

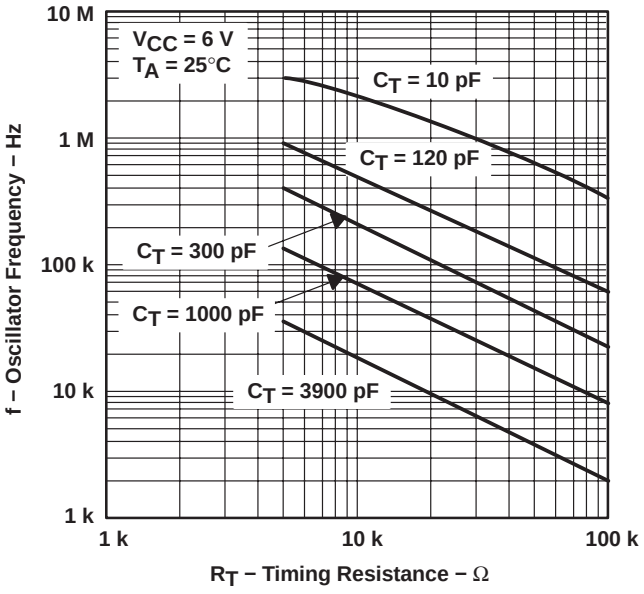


Figure 6

OSCILLATOR PERIOD vs TIMING CAPACITANCE

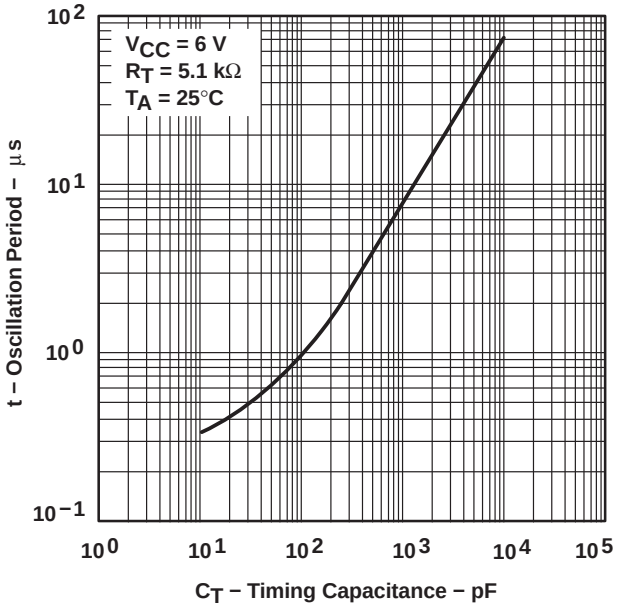


Figure 7

OSCILLATOR FREQUENCY vs FREE-AIR TEMPERATURE

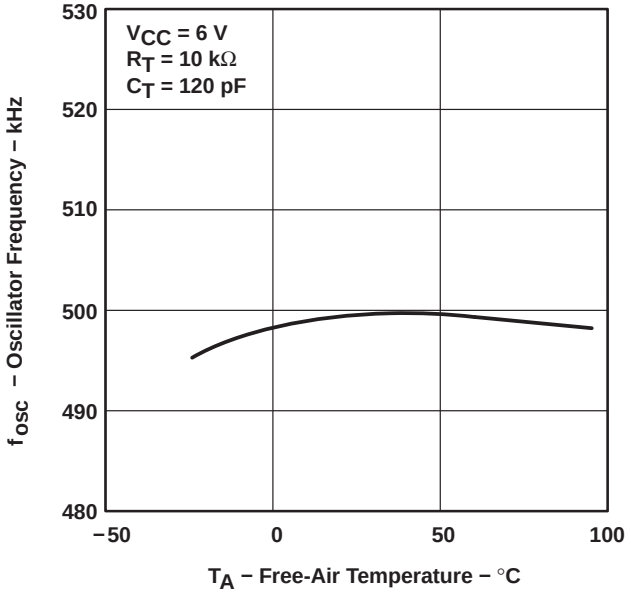


Figure 8

PWM TRIANGLE WAVEFORM AMPLITUDE vs TIMING CAPACITANCE

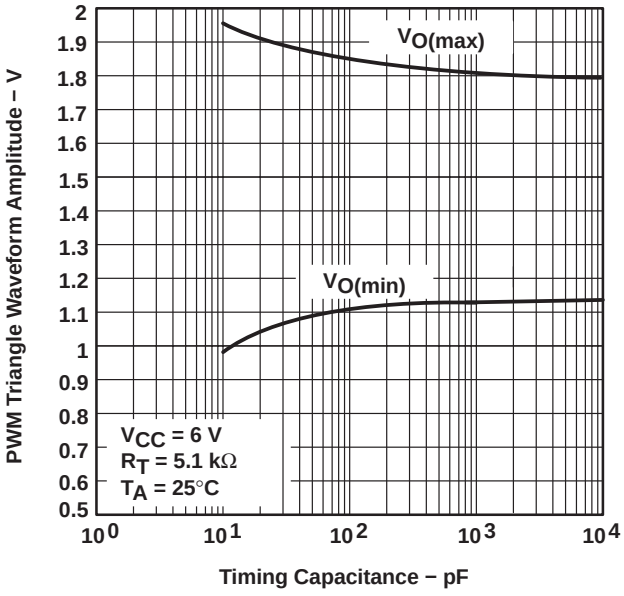


Figure 9

TYPICAL CHARACTERISTICS

DTC INPUT THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE

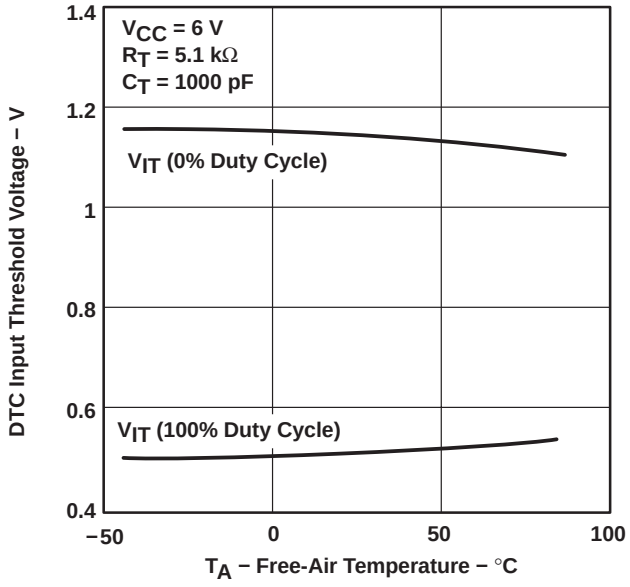


Figure 10

SCP TIME-OUT PERIOD vs SCP CAPACITANCE

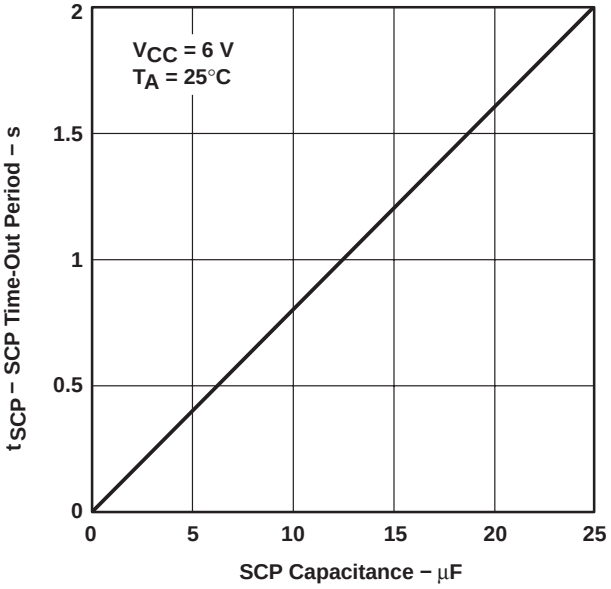


Figure 11

SCP THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE

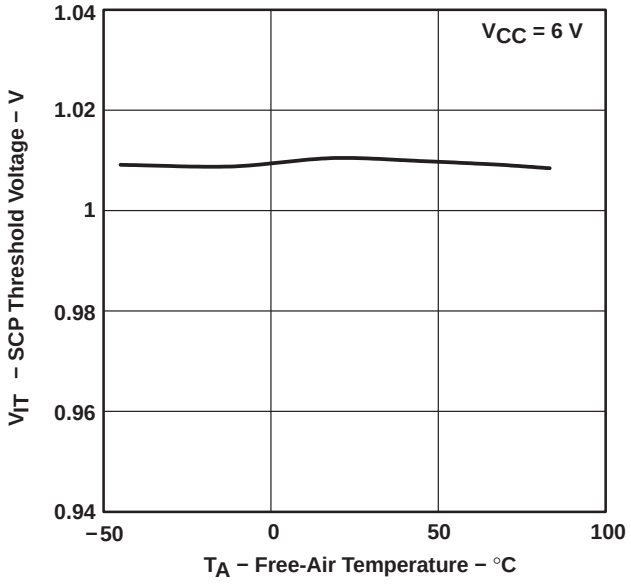


Figure 12

SCP LATCH RESET VOLTAGE vs FREE-AIR TEMPERATURE

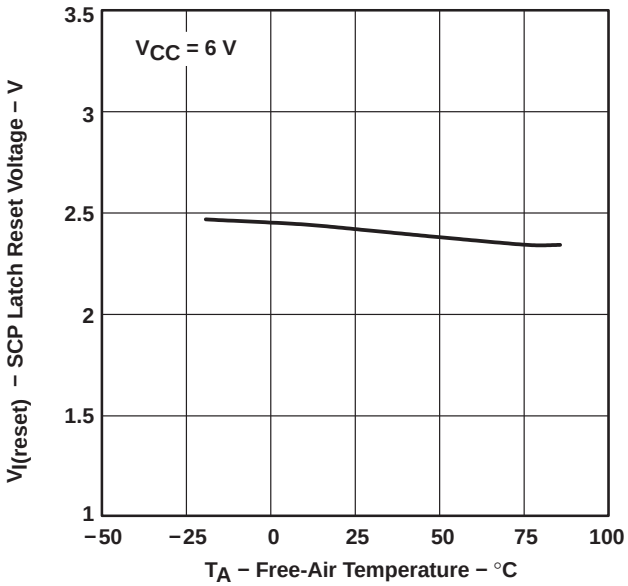


Figure 13

TYPICAL CHARACTERISTICS

UVLO THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE

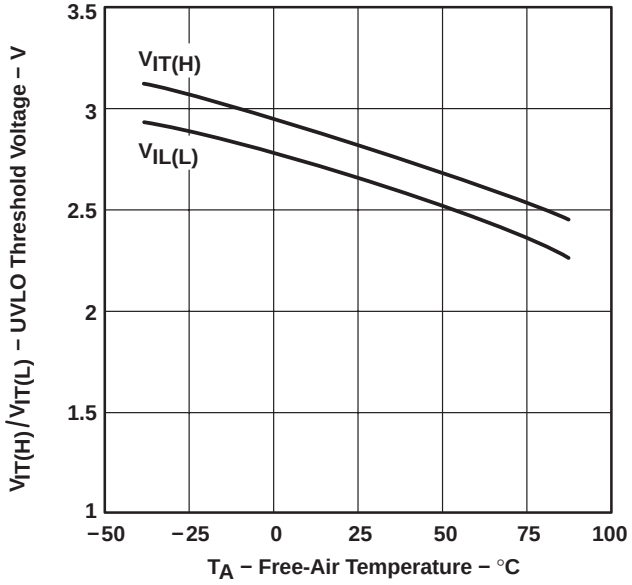


Figure 14

DUTY CYCLE vs DTC INPUT VOLTAGE

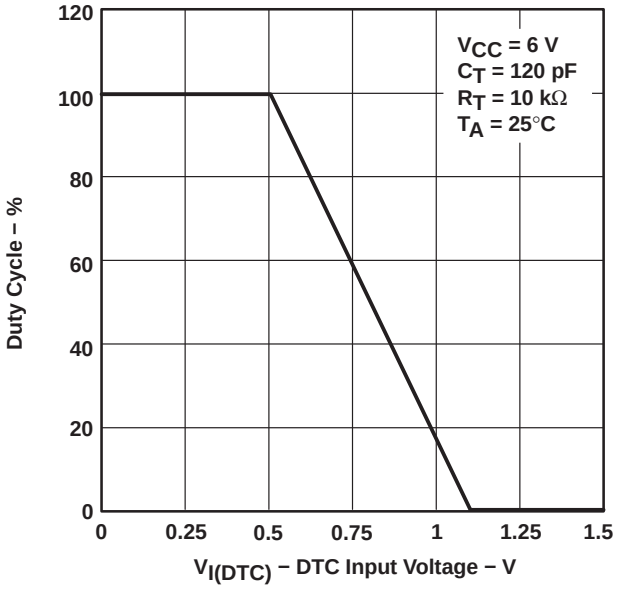


Figure 15

ERROR-AMPLIFIER MAXIMUM OUTPUT VOLTAGE vs SOURCE CURRENT

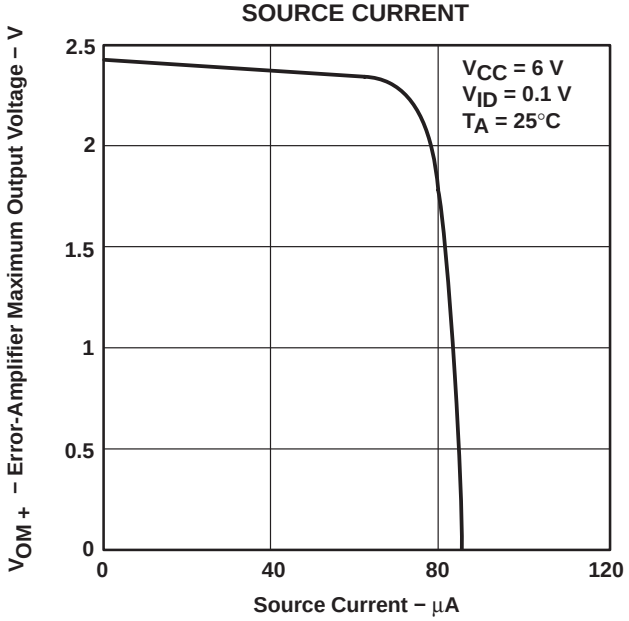


Figure 16

ERROR-AMPLIFIER MINIMUM OUTPUT VOLTAGE vs SINK CURRENT

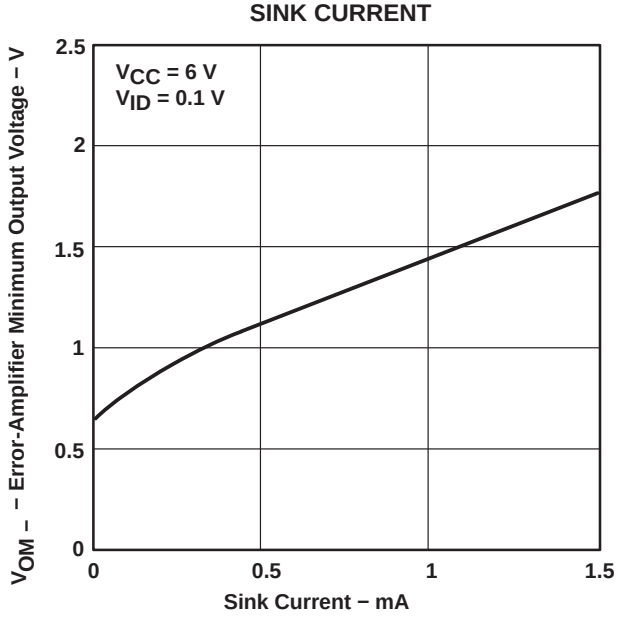


Figure 17

TYPICAL CHARACTERISTICS

ERROR AMPLIFIER MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE SWING vs FREQUENCY

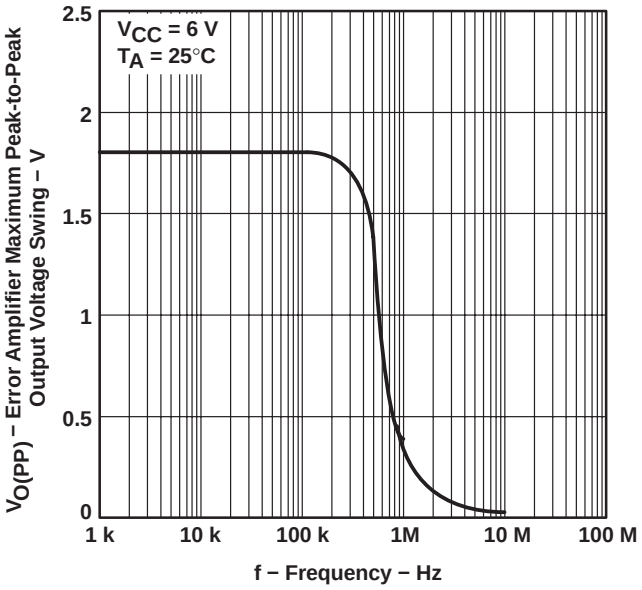


Figure 18

ERROR-AMPLIFIER MINIMUM OUTPUT VOLTAGE SWING vs FREE-AIR TEMPERATURE

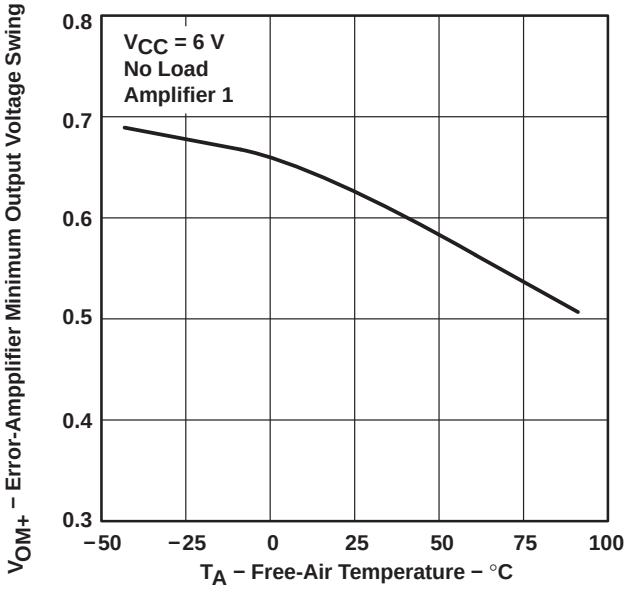


Figure 19

ERROR AMPLIFIER OPEN-LOOP GAIN AND PHASE SHIFT vs FREQUENCY

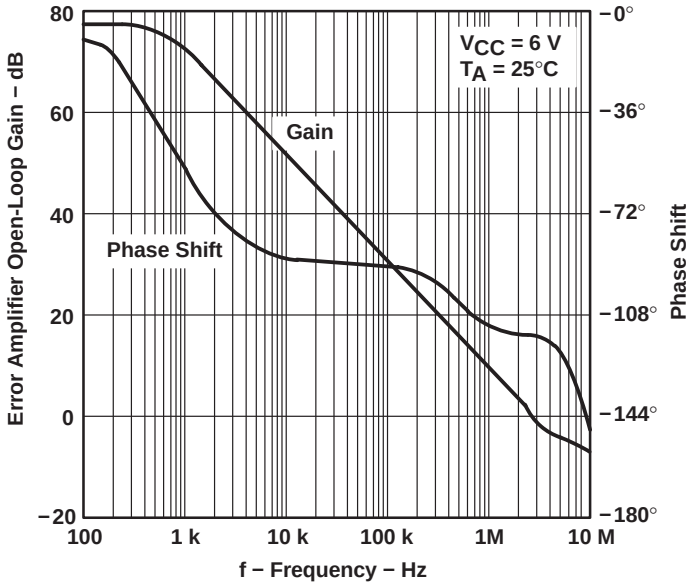


Figure 20

TYPICAL CHARACTERISTICS

ERROR-AMPLIFIER POSITIVE OUTPUT VOLTAGE SWING vs FREE-AIR TEMPERATURE

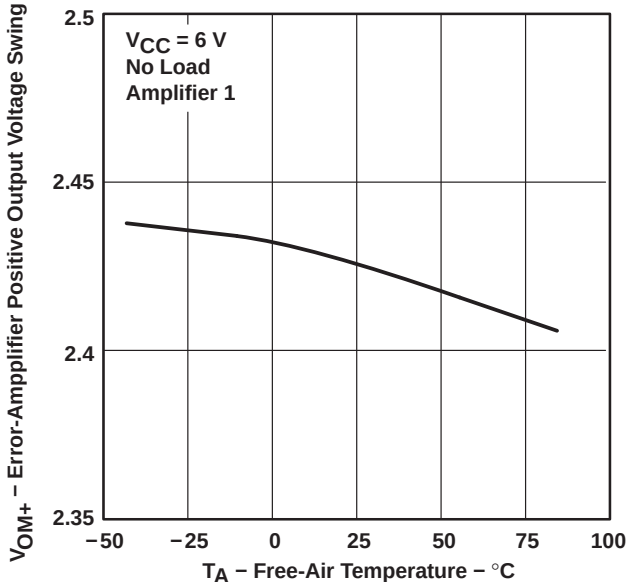


Figure 21

HIGH-LEVEL OUTPUT VOLTAGE vs OUTPUT CURRENT

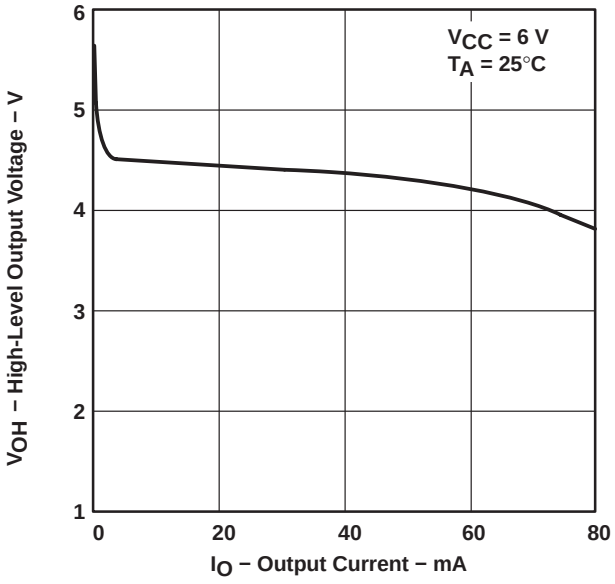


Figure 22

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

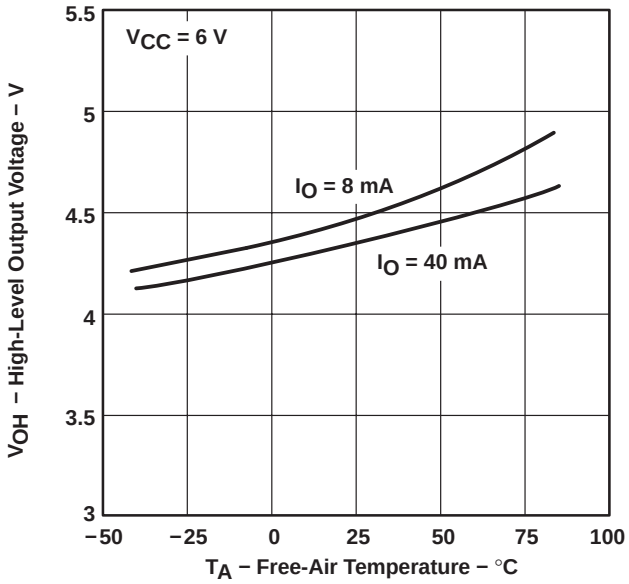


Figure 23

TYPICAL CHARACTERISTICS

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

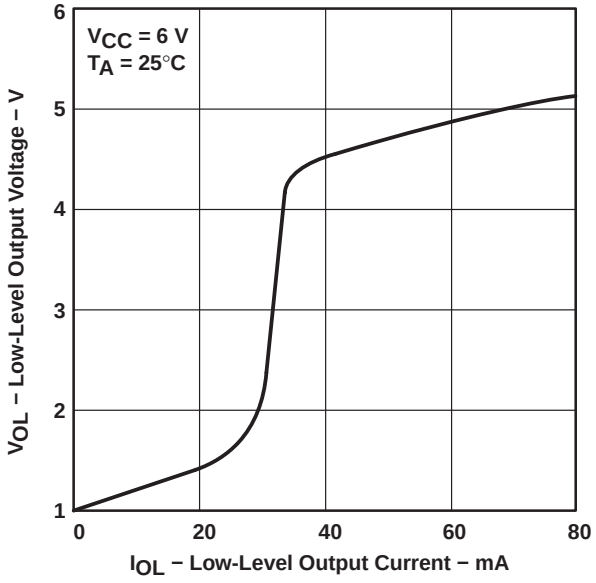


Figure 24

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

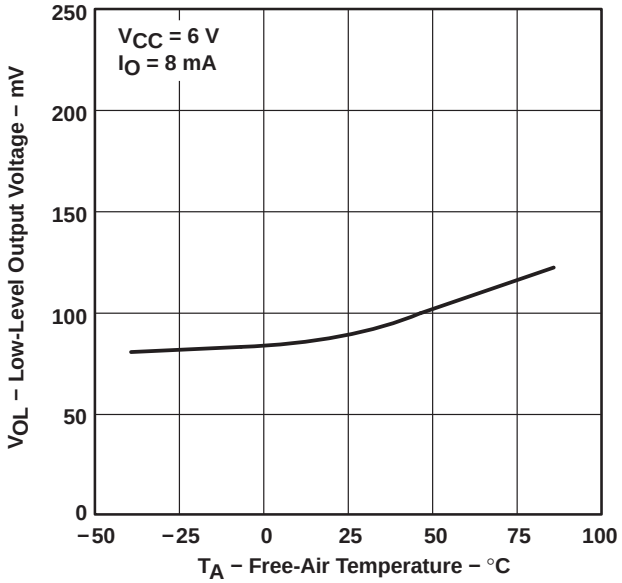


Figure 25

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

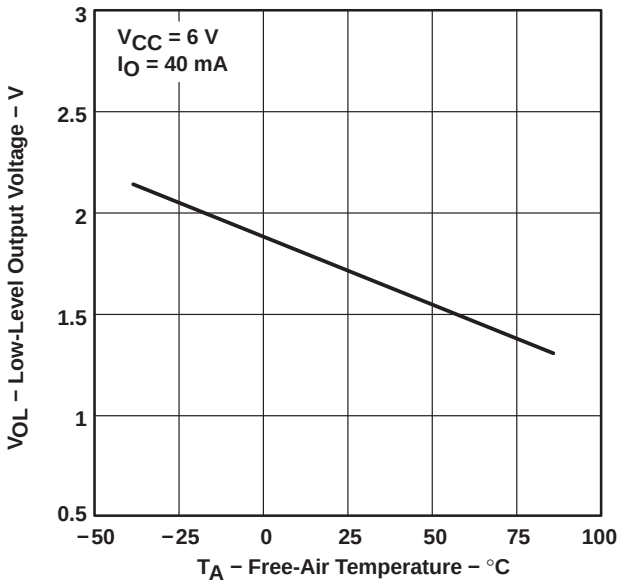


Figure 26

AVERAGE SUPPLY CURRENT vs FREE-AIR TEMPERATURE

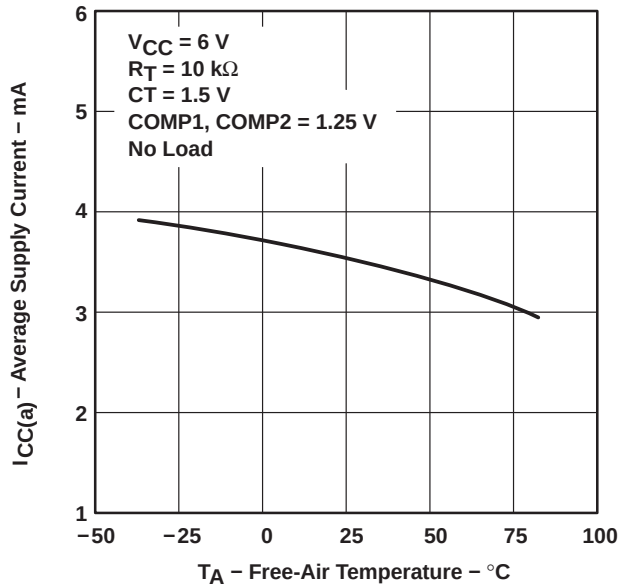


Figure 27

TYPICAL CHARACTERISTICS

STANDBY SUPPLY CURRENT vs SUPPLY VOLTAGE

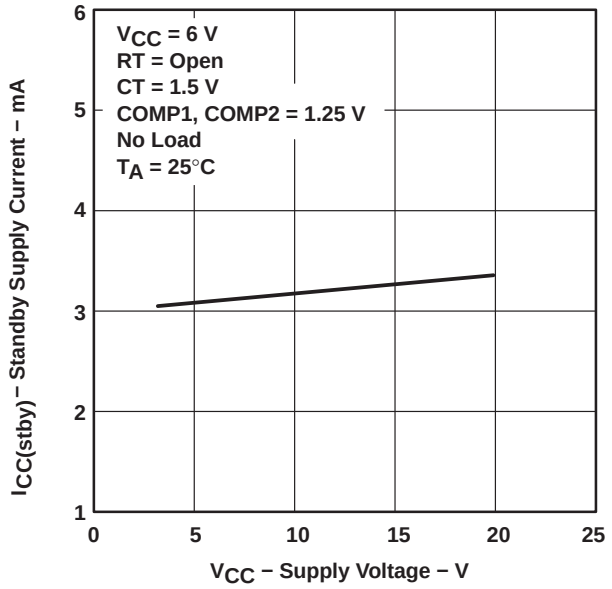


Figure 28

STANDBY SUPPLY CURRENT vs FREE-AIR TEMPERATURE

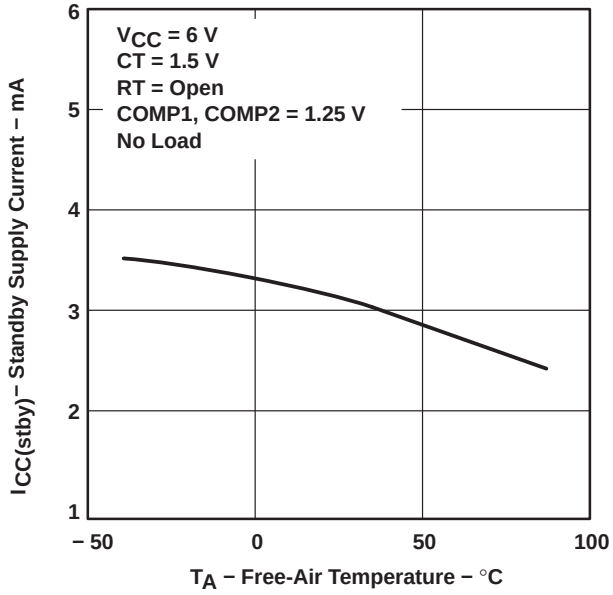


Figure 29

REFERENCE VOLTAGE vs SUPPLY VOLTAGE

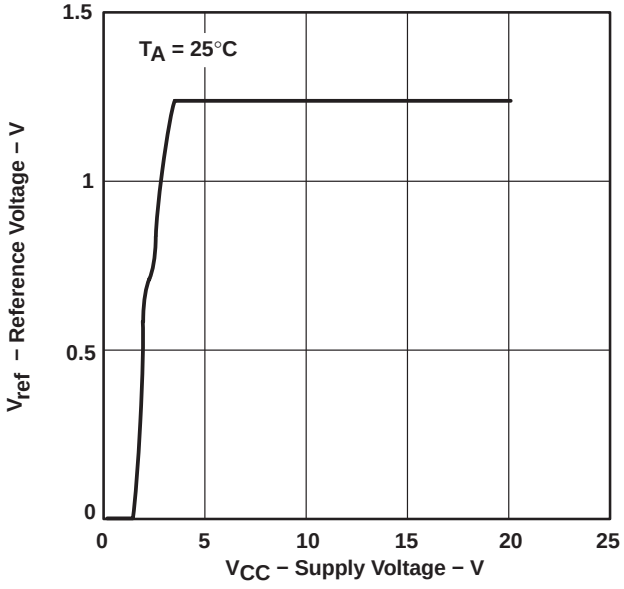


Figure 30

REFERENCE VOLTAGE vs SUPPLY VOLTAGE

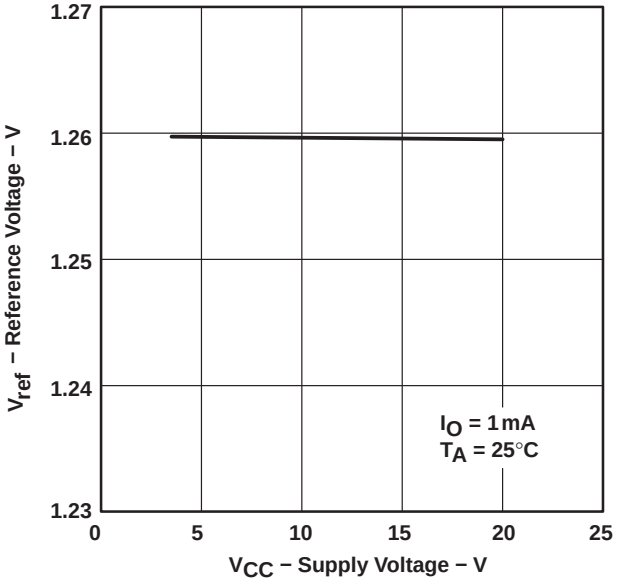


Figure 31

TYPICAL CHARACTERISTICS

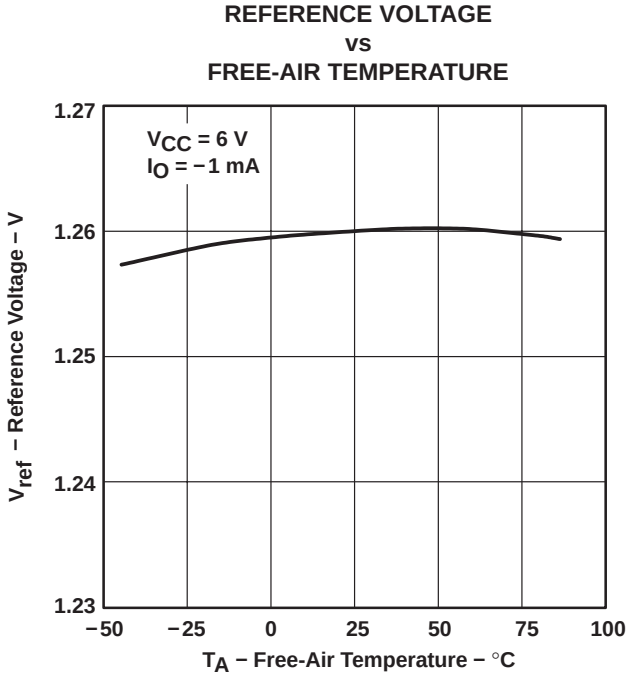


Figure 32

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL1454ACD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	TL1454AC	Samples
TL1454ACDB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	T1454A	Samples
TL1454ACDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	T1454A	Samples
TL1454ACDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	TL1454AC	Samples
TL1454ACDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	TL1454AC	Samples
TL1454ACN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-20 to 85	TL1454ACN	Samples
TL1454ACNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	TL1454A	Samples
TL1454ACPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	T1454A	Samples
TL1454ACPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	T1454A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

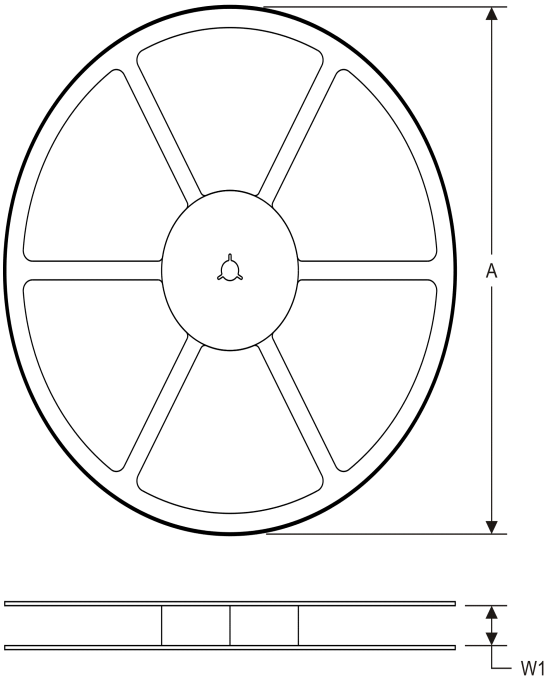
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

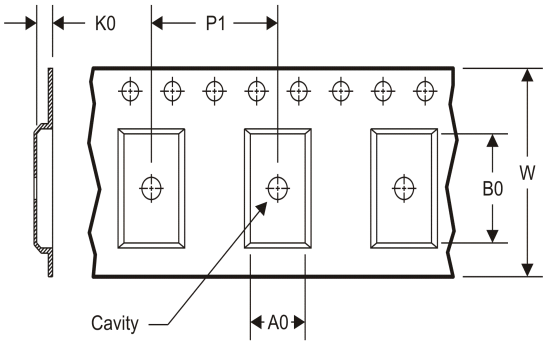
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



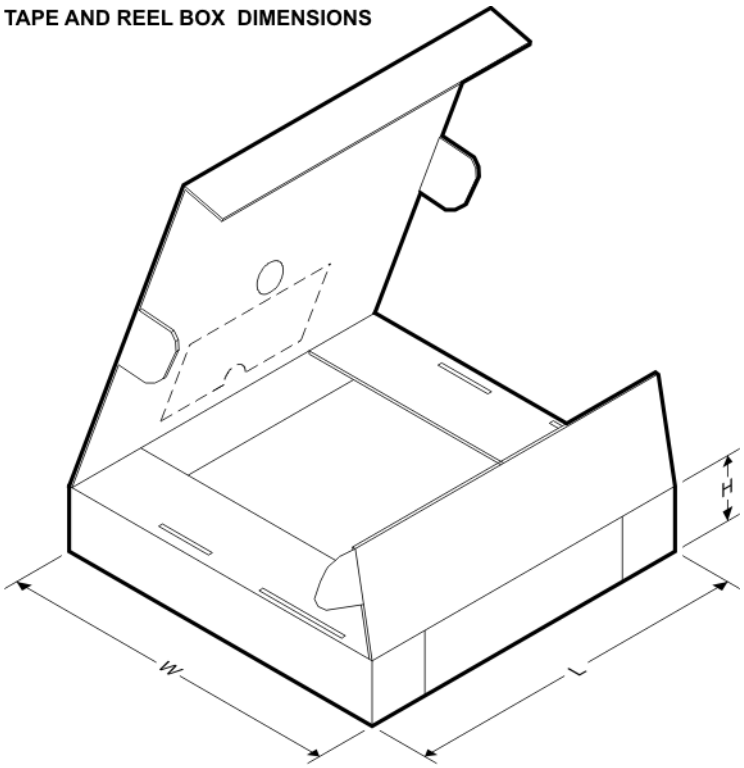
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL1454ACDBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL1454ACDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL1454ACDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL1454ACNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL1454ACPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL1454ACDBR	SSOP	DB	16	2000	367.0	367.0	38.0
TL1454ACDR	SOIC	D	16	2500	367.0	367.0	38.0
TL1454ACDR	SOIC	D	16	2500	333.2	345.9	28.6
TL1454ACNSR	SO	NS	16	2000	367.0	367.0	38.0
TL1454ACPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

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